

Listing of Claims:

This listing of claims is provided for ease of reference:

1. (Withdrawn) A circuit device comprising:
a first circuit element having a hollow inside;
a plurality of second circuit elements electrically connected to the first circuit element; and
sealing resin for covering the first and second circuit elements,
wherein the distances by which the first circuit element is separated from the second circuit elements are longer than those by which the second circuit elements are separated from each other.
2. (Withdrawn) The circuit device according to claim 1, wherein the second circuit elements are located closer to a central portion of the sealing resin than the first circuit element is.
3. (Withdrawn) The circuit device according to claim 1, wherein the first circuit element is located closer to a peripheral portion of the sealing resin than the second circuit elements are.
4. (Withdrawn) The circuit device according to claim 1, wherein the first circuit element is a SAW filter.
5. (Withdrawn) A circuit device comprising:
a first circuit element having a hollow therein;
a plurality of second circuit elements electrically connected to the first circuit element; and
a sealing resin covering the first and second circuit elements,
wherein the first circuit element is disposed in a more peripheral area of the sealing resin than the second circuit elements, and a separated distance between the first and second circuit elements is longer than a separated distance between the second circuit elements.

6. (Withdrawn) The circuit device according to claim 5, wherein the first circuit element is located in a vicinity of an end portion of the sealing resin in a longitudinal direction, and the second circuit element is located in a vicinity of a central portion of the sealing resin in the longitudinal direction.

7. (Cancelled)

8. (Withdrawn) The circuit device according to claim 5, wherein the first circuit element is a SAW filter.

9. (Withdrawn) A circuit device, comprising:

a first circuit element fixed to a first land and having a hollow therein;

a second circuit element separated from the first land and fixed to a second land disposed in a vicinity of a central area;

a first lead whose one end is led out to outside and the other end is connected to the first or second circuit elements;

a second lead connecting the first and second circuit elements;

a third lead extending in a manner of connecting the first and second lands and formed to have a narrower width than those of the first and second lands; and

a sealing resin sealing each of the circuit elements and each of the leads.

10. (Withdrawn) The circuit device according to claim 9, wherein the first circuit element is a SAW filter.

11. (Withdrawn) The circuit device according to claim 9, wherein the second circuit element is any one of a semiconductor element for processing any one of a video signal and an image signal, a semiconductor element for processing information associated with the video signal, and a CCD for delaying an electrical signal.

12. (Withdrawn) The circuit device according to claim 9, wherein any one of the first and second circuit elements is connected to any one of the first and second leads through a fine metal wire.

13. (Withdrawn) A method of manufacturing a circuit device, comprising the steps of:

placing a first circuit element having a hollow inside and a second circuit element electrically connected to the first circuit element in a cavity of a molding die; and

sealing the first and second circuit elements with resin by filling sealing resin from a gate into the cavity,

wherein the first circuit element is located farther away from the gate than the second circuit element is.

14. (Withdrawn) The method according to claim 13,
wherein the cavity forms a long and narrow space,
the gate is formed in an end portion of the cavity in a longitudinal direction, and
the first circuit element is located in a vicinity of an end portion opposite to the gate inside the cavity.

15. (Withdrawn) The method according to claim 13, wherein thermosetting resin is adopted as the sealing resin.

16. (Previously presented) A circuit device, comprising:
a SAW filter having a hollow therein;
a semiconductor element electrically connected to the SAW filter; and
a sealing resin covering the SAW filter and the semiconductor element,
wherein the SAW filter and the semiconductor element are sealed by enclosing the sealing resin from a gate in a cavity molded with a mold, and a distance between the SAW filter and the gate is greater than a distance between the semiconductor element and the gate.

17. (Previously presented) The circuit device according to claim 16, wherein the gate is positioned at an edge in a lengthwise direction of the sealing resin, and the SAW filter is disposed in a vicinity of the edge opposed to the gate.

18. (Previously presented) The circuit device according to claim 16, wherein the semiconductor element is among a plurality of semiconductor elements, wherein the plurality of semiconductor elements are disposed in a vicinity of a central area of the sealing resin, and the SAW filter is disposed in a more peripheral area than the semiconductor elements.

19. (Previously presented) The circuit device according to claim 16, wherein the semiconductor element is any one of a semiconductor element for processing any one of a video signal and an image signal, a semiconductor element for processing information associated with the video signal, and a CCD for delaying an electrical signal.

20. (Previously presented) The circuit device according to claim 16, wherein any one of the SAW filter and semiconductor element is connected to any one of a first lead and a second lead through a fine metal wire.

21. (Previously presented) The circuit device according to claim 18, wherein distances between the SAW filter and individual semiconductor elements of the plurality of semiconductor elements is greater than distances between each of the plurality of semiconductor elements.

22. (Previously presented) The circuit device according to claim 16, wherein the SAW filter is located closer to a peripheral portion of the sealing resin than the semiconductor element is.